

COPPER/COPPER ALLOY SURFACE BONDING PROMOTOR AND ITS USAGE

ABSTRACT OF THE DISCLOSURE

5 A halogen ion/hydrogen peroxide-free copper/copper alloy surface bonding promotor includes copper oxidant 0.1~20wt%, acidic solution prepared from organic acid, inorganic acid, or their compound 5~20wt%, and nonionic compound 0.001~10wt%. The use of the halogen ion/hydrogen peroxide-free copper/copper alloy
10 surface bonding promotor enables the copper/copper alloy to have a rough surface that exhibits excellent adhesion to resins and superior solderability.